

ABSTRACT

Provided is a tape for semiconductor processing, with which a semiconductor wafer can be satisfactorily divided into individual chips at the time of dicing, and the occurrence of package cracks can be prevented at the time of packaging. The tape for semiconductor processing 10 of the invention includes a dicing tape 13 having a base film 11 and a pressure-sensitive adhesive layer 12; a metal layer 14 provided on the pressure-sensitive adhesive layer 12 for protecting the back surface of a semiconductor chip; and an adhesive layer 15 provided on the metal layer 14 for adhering the metal layer 14 to the back surface of a semiconductor chip, in which the surface roughness RzJIS of the metal layer 14 based on the 10-point average roughness is 0.5 μm or more and less than 10.0 μm .